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<sup>1</sup>Daegu Gyeongbuk Institute of Science and Technology, Korea; <sup>2</sup>IBM Research GmbH, Switzerland

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**Chair(s):** Makoto Takamiya, *University of Tokyo*  
Francesco Rezzi, *Inventvm*

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<sup>1</sup>Peking University, China; <sup>2</sup>Li Auto Inc., China; <sup>3</sup>Chinese Institute for Brain Research, China

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<sup>1</sup>Sungkyunkwan University, Korea; <sup>2</sup>Samsung Electronics Co., Korea; <sup>3</sup>University at Buffalo, The State University of New York, United States

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<sup>1</sup>Vrije Universiteit Brussel, Belgium; <sup>2</sup>Ghent University, Belgium; <sup>3</sup>IMEC, Belgium

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**Date:** Wednesday, September 10, 2025

**Room:** Audimax TUM

**Chair(s):** Ralf Brederlow, *TU Munich*

### **Unlocking the Future: Quantum Technologies in the Era of Solid-State Electronics**

Johanna Sepúlveda

*Airbus Defence and Space, Germany*

## **Keynote IV**

**Date:** Wednesday, September 10, 2025

**Room:** Audimax TUM

**Chair(s):** Maurits Ortmanns, *University of Ulm*

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*Yonsei University / XO Semiconductor Inc., Korea*

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**Date:** Wednesday, September 10, 2025

**Room:** Audimax TUM

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<sup>1</sup>Forschungszentrum Juelich GmbH, Germany; <sup>2</sup>AdMOS GmbH, Germany; <sup>3</sup>Racyics GmbH, Germany; <sup>4</sup>GlobalFoundries, Germany; <sup>5</sup>Fraunhofer IPMS, Germany; <sup>6</sup>University Duisburg-Essen, Germany; <sup>7</sup>GlobalFoundries, Belgium

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<sup>1</sup>National Cheng Kung University, Taiwan; <sup>2</sup>National Center for High-performance Computing, Taiwan; <sup>3</sup>Institute of Pioneer Semiconductor Innovation, National Yang Ming Chiao Tung University, Taiwan

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**Date:** Wednesday, September 10, 2025

**Room:** Room 0670

**Chair(s):** Suhwan Kim, *Intel*  
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<sup>1</sup>*National Yang Ming Chiao Tung University, Taiwan;* <sup>2</sup>*Realtek Semiconductor Corp., Taiwan*

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<sup>1</sup>*National Yang Ming Chiao Tung University, Taiwan;* <sup>2</sup>*Realtek Semiconductor Corp., Taiwan*

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<sup>1</sup>*Korea University, Korea;* <sup>2</sup>*Samsung Electronics Co., Ltd., Korea*

# Digital Circuits and Techniques

**Date:** Wednesday, September 10, 2025

**Room:** Room 1601

**Chair(s):** Martin Brox, *Micron Technologies*  
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**Date:** Wednesday, September 10, 2025

**Room:** Room 0606

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<sup>1</sup>*Brigham Young University, United States*; <sup>2</sup>*National Taiwan University, Taiwan*;

<sup>3</sup>*National Yang Ming Chiao Tung University, Taiwan*; <sup>4</sup>*University of Utah, United States*;

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<sup>1</sup>*University of California, San Diego, United States*; <sup>2</sup>*UNIST, Korea*; <sup>3</sup>*Sogang University, Korea*;

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<sup>1</sup>*Zhejiang University, China*; <sup>2</sup>*IMEC, Belgium*

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# ML Dataflow Acceleration with SRAM Compute-in-Memory

**Date:** Wednesday, September 10, 2025

**Room:** Room 0602

**Chair(s):** Hongyang Jia, *Tsinghua University*  
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<sup>1</sup>*National Taiwan University, Taiwan*; <sup>2</sup>*MediaTek Inc., Taiwan*

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## Advanced TCAD

**Date:** Wednesday, September 10, 2025

**Room:** Room 0601

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<sup>1</sup>Hitachi Energy, Switzerland; <sup>2</sup>Hitachi Energy, Canada; <sup>3</sup>Hitachi Energy, Poland

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<sup>1</sup>Indian Institute of Technology Delhi, India; <sup>2</sup>CROMA, Université Grenoble Alpes, Université  
Savoie Mont Blanc, CNRS, Grenoble INP, France

# Wireline Clock Generation and High Performance On-Chip Links

**Date:** Wednesday, September 10, 2025

**Room:** Room 1100

**Chair(s):** Harijot Singh Bindra, *University of Twente*  
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<sup>1</sup>*Hong Kong University of Science and Technology, Hong Kong*; <sup>2</sup>*Sharif University of Technology, Iran*; <sup>3</sup>*University of Tehran, Iran*

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<sup>1</sup>*Texas A&M University, United States*; <sup>2</sup>*Samsung Electronics Co., Ltd., Korea*; <sup>3</sup>*Hanyang University, Korea*

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<sup>1</sup>*Soongsil University, Korea*; <sup>2</sup>*Korea Electronics Technology Institute, Korea*

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<sup>1</sup>*KAIST, Korea*; <sup>2</sup>*MediaTek Inc., United States*; <sup>3</sup>*Samsung Electronics Co., Ltd., Korea*

## Emerging Memory

**Date:** Wednesday, September 10, 2025

**Room:** Audimax TUM

**Chair(s):** Wolfgang Gös, *SILVACO Europe*  
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<sup>1</sup>*Seoul National University, Korea*; <sup>2</sup>*National University of Singapore, Singapore*

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**Date:** Wednesday, September 10, 2025

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<sup>1</sup>National University of Singapore, Singapore; <sup>2</sup>NXP Semiconductors N.V., United States;

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<sup>1</sup>Zhejiang University, China; <sup>2</sup>Yongjiang Laboratory, China

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**Date:** Wednesday, September 10, 2025

**Room:** Room 0670

**Chair(s):** Danilo Manstretta, *University of Pavia*  
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**Date:** Wednesday, September 10, 2025

**Room:** Room 1601

**Chair(s):** Luca Bertulesi, *Politecnico de Milano*  
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**Date:** Wednesday, September 10, 2025

**Room:** Room 0606

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**Date:** Wednesday, September 10, 2025

**Room:** Room 0602

**Chair(s):** Richard Gaggl, *Infineon*  
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**Date:** Wednesday, September 10, 2025

**Room:** Room 0601

**Chair(s):** Carolina Mora Lopez, *IMEC*  
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<sup>1</sup>POSTECH, Korea; <sup>2</sup>Samsung Electronics Co., Ltd., Korea; <sup>3</sup>Sejong University, Korea; <sup>4</sup>Hanbat National University, Korea

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<sup>1</sup>*Globalfoundries, United States*; <sup>2</sup>*Globalfoundries, Germany*

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**Date:** Thursday, September 11, 2025

**Room:** Audimax TUM

**Chair(s):** Maurits Ortmanns, *University of Ulm*

### **From Test Tools to High-NA and Beyond: ZEISS's Role in Advancing EUV Lithography**

Peter Kuerz

*Carl Zeiss SMT GmbH, Germany*

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**Date:** Thursday, September 11, 2025

**Room:** Audimax TUM

**Chair(s):** Manuel Le Gallo, *IBM*  
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<sup>1</sup>POSTECH, Korea; <sup>2</sup>KAIST, Korea

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<sup>1</sup>Peking University, China; <sup>2</sup>University of Science and Technology of China, China; <sup>3</sup>Beijing Advanced Innovation Center for Integrated Circuits, China

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**Date:** Thursday, September 11, 2025

**Room:** Room 0670

**Chair(s):** Yang Zhang, *imec*  
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*<sup>1</sup>Southeast University, China; <sup>2</sup>Purple Mountain Laboratory, China*

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**Date:** Thursday, September 11, 2025

**Room:** Room 1601

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<sup>1</sup>*Boston University, United States*; <sup>2</sup>*Technische Universität München, Germany*; <sup>3</sup>*Massachusetts Institute of Technology, United States*; <sup>4</sup>*Northeastern University, United States*

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<sup>1</sup>*University of California, San Diego, United States*; <sup>2</sup>*Hanyang University, Korea*; <sup>3</sup>*Samsung Electronics Co., Korea*

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**Date:** Thursday, September 11, 2025

**Room:** Room 0606

**Chair(s):** Istvan Gyongy, *University Of Edinburgh*  
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<sup>1</sup>*École Polytechnique Fédérale de Lausanne, Switzerland;* <sup>2</sup>*Globalfoundries, Singapore*

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**Date:** Thursday, September 11, 2025

**Room:** Room 0602

**Chair(s):** Burak Conen, *StarIC*  
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**Date:** Thursday, September 11, 2025  
**Room:** Room 0601  
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**Date:** Thursday, September 11, 2025  
**Room:** Room 1100  
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